



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE5009 E2010		<b>Issued</b>		18. August 2019		
<b>MA#</b>		MA000983854						
<b>Package</b>		PG-DSO-8-16		<b>Weight*</b>		83.18 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.725	2.07	2.07	20743	20743
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		431	
	non noble metal	iron	7439-89-6	0.717	0.86		8622	
wire	non noble metal	copper	7440-50-8	29.121	35.01	35.92	350078	359239
	noble metal	gold	7440-57-5	0.211	0.25	0.25	2539	2539
	encapsulation	organic material	carbon black	1333-86-4	0.098	0.12		1174
plastics	plastics	epoxy resin	-	4.492	5.40		53999	
	inorganic material	silicondioxide	60676-86-0	44.235	53.19	58.71	531768	586941
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9784	9784
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7817	7817
glue	plastics	acrylic resin	-	0.237	0.28		2846	
	noble metal	silver	7440-22-4	0.839	1.01	1.29	10091	12937
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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